

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AKIRA NISHIOKA	07/31/2014
MASAKI MIZUOCHI	07/31/2014
SHUICHI NAKAGAWA	08/04/2014
HIROSHI TSUJI	08/09/2014
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION
Street Address:	24-14, NISHI SHIMBASHI 1-CHOME
Internal Address:	MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-8717
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14463263
CORRESPONDENCE DATA	
Fax Number:	(202)756-8087
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-756-8000
Email:	mweipdocket@mwe.com
Correspondent Name:	MCDERMOTT WILL & EMERY LLP
Address Line 1:	THE MCDERMOTT BUILDING
Address Line 2:	500 NORTH CAPITOL STREET, N.W.
Address Line 4:	WASHINGTON, D.C. 20001
ATTORNEY DOCKET NUMBER:	075905-0175
NAME OF SUBMITTER:	TARA JEFFERS
SIGNATURE:	/tara jeffers/
DATE SIGNED:	09/10/2014
Total Attachments: 1	
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ASSIGNMENT

(讓 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi, 1-chome, Minato-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

STAGE APPARATUS, AND CHARGED PARTICLE BEAM APPARATUS USING SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Akira Nishioka</u> Akira NISHIOKA	<u>7/31/2014</u>
2)	<u>Masaki Mizuochi</u> Masaki MIZUOCHI	<u>7/31/2014</u>
3)	<u>Shuichi Nakagawa</u> Shuichi NAKAGAWA	<u>8/4/2014</u>
4)	<u>Hiroshi Tsuji</u> Hiroshi TSUJI	<u>8/9/2014</u>